

Special Issue

Transfer Learning and Data Augmentation in Engineering: Bridging Gaps for Smart Industrial Solutions

Message from the Guest Editor

This Special Issue aims to gather high-quality research that explores innovative methods, theories, and applications related to transfer learning and data augmentation in various engineering contexts. We welcome contributions that advance fundamental methodologies, propose novel architectures or frameworks, and demonstrate real-world deployments in industrial scenarios such as manufacturing, fault diagnosis, predictive maintenance, robotics, autonomous systems, and more.

We welcome the submission of both theoretical and empirical studies that address domain adaptation, cross-domain feature alignment, synthetic data generation, weakly supervised learning, and applications involving edge computing or real-time industrial AI systems. By bridging the gap between data scarcity and intelligent solutions, this Special Issue seeks to foster interdisciplinary insights that promote robust, scalable, and trustworthy engineering systems.

Guest Editor

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Message from the Editor-in-Chief

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